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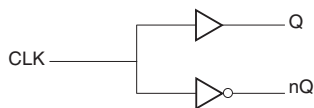
GENERAL DESCRIPTION

The 8302I-01 is a low skew, 1-to-2 LVCMOS/LVTTTL Fanout Buffer w/Complementary Output. The 8302I-01 has a single ended clock input. The single ended clock input accepts LVCMOS or LVTTTL input levels. The 8302I-01 is characterized at full 3.3V for input V_{DD} , and mixed 3.3V and 2.5V for output operating supply modes (V_{DDO}). Guaranteed output and part-to-part skew characteristics make the 8302I-01 ideal for clock distribution applications demanding well defined performance and repeatability.

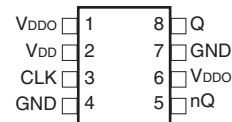
FEATURES

- Complementary LVCMOS / LVTTTL output
- LVCMOS / LVTTTL clock input accepts LVCMOS or LVTTTL input levels
- Maximum output frequency: 250MHz
- Output skew: 165ps (maximum)
- Part-to-part skew: 800ps (maximum)
- Small 8 lead SOIC package saves board space
- Full 3.3V or 3.3V core/2.5V output supply modes
- -40°C to 85°C ambient operating temperature
- Available in lead-free compliant package

BLOCK DIAGRAM



PIN ASSIGNMENT



**8302I-01
8-Lead SOIC**

3.8mm x 4.8mm, x 1.47mm package body

**M Package
Top View**

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 6	V _{DDO}	Power		Output supply pins.
2	V _{DD}	Power		Power supply pin.
3	CLK	Input	Pulldown	LVC MOS / LV TTL clock input.
4,7	GND	Power		Power supply ground.
5	nQ	Output		Complementary clock output. LVC MOS / LV TTL interface levels.
8	Q	Output		Clock output. LVC MOS / LV TTL interface levels.

NOTE: *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
C _{PD}	Power Dissipation Capacitance (per output)	V _{DD} , V _{DDO} = 3.465V		22		pF
		V _{DD} = 3.465V, V _{DDO} = 2.625V		16		pF
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ
R _{OUT}	Output Impedance		5	7	12	Ω

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to $V_{DD} + 0.5V$
Outputs, V_O	-0.5V to $V_{DDO} + 0.5V$
Package Thermal Impedance, θ_{JA}	112.7°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 3.3V \pm 5\%$ OR $2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Power Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Power Supply Voltage		3.135	3.3	3.465	V
			2.375	2.5	2.625	V
I_{DD}	Power Supply Current				13	mA
I_{DDO}	Output Supply Current				4	mA

TABLE 3B. LVCMOS / LVTTTL DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 3.3V \pm 5\%$ OR $2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage		2		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage		-0.3		0.8	V
I_{IH}	Input High Current	CLK $V_{DD} = V_{IN} = 3.465V$			150	μA
I_{IL}	Input Low Current	CLK $V_{DD} = 3.465V, V_{IN} = 0V$	-5			μA
V_{OH}	Output High Voltage	$V_{DDO} = 3.465, 50\Omega$ to $V_{DDO}/2$	2.6			V
		$V_{DDO} = 3.465, I_{OH} = -100\mu\text{A}$	2.9			V
		$V_{DDO} = 2.625, 50\Omega$ to $V_{DDO}/2$	1.8			V
		$V_{DDO} = 2.625, I_{OH} = -100\mu\text{A}$	2.2			V
V_{OL}	Output Low Voltage	$V_{DDO} = 3.465, 50\Omega$ to $V_{DDO}/2$			0.5	V
		$V_{DDO} = 3.465, I_{OL} = 100\mu\text{A}$			0.2	V
		$V_{DDO} = 2.625, 50\Omega$ to $V_{DDO}/2$			0.5	V
		$V_{DDO} = 2.625, I_{OL} = 100\mu\text{A}$			0.2	V

TABLE 4A. AC CHARACTERISTICS, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				250	MHz
tp_{LH}	Propagation Delay, Low-to-High; NOTE 1		1.8		2.7	ns
$tsk(o)$	Output Skew; NOTE 2, 4				165	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4				800	ps
t_R / t_F	Output Rise/Fall Time	20% to 80%	300		800	ps
odc	Output Duty Cycle	$f \leq 133\text{MHz}$	45		55	%
		$133\text{MHz} < f \leq 250\text{MHz}$	40		60	%

NOTE 1: Measured from $V_{DD}/2$ of the input to $V_{DDO}/2$ of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at $V_{DDO}/2$.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDO}/2$.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

TABLE 4B. AC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				250	MHz
tp_{LH}	Propagation Delay, Low-to-High; NOTE 1		1.9		2.9	ns
$tsk(o)$	Output Skew; NOTE 2, 4				250	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4				900	ps
t_R / t_F	Output Rise/Fall Time	20% to 80%	100		850	ps
odc	Output Duty Cycle	$f \leq 133\text{MHz}$	45		55	%
		$133\text{MHz} < f \leq 250\text{MHz}$	40		60	%

NOTE 1: Measured from $V_{DD}/2$ of the input to $V_{DDO}/2$ of the output.

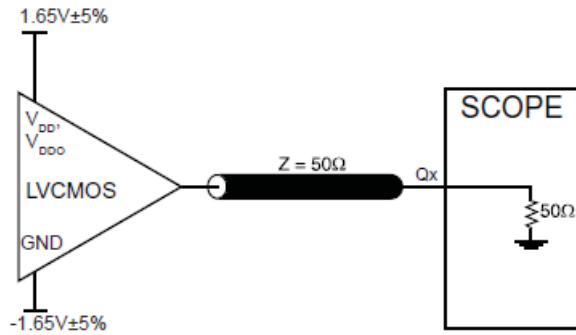
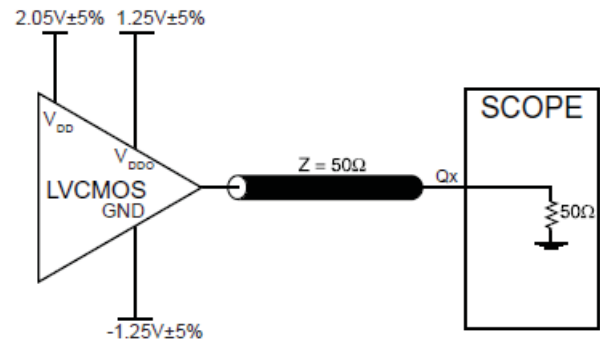
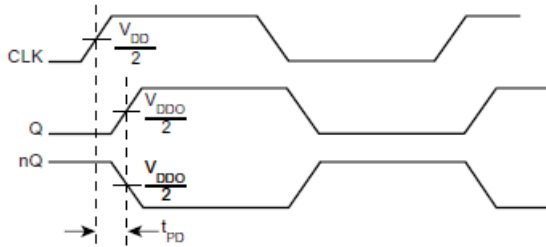
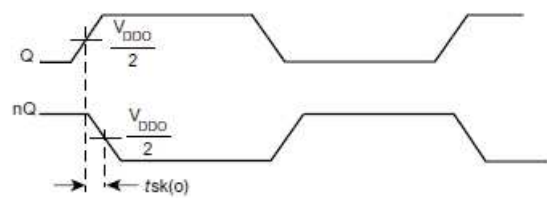
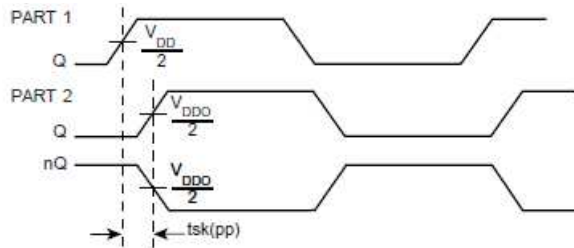
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

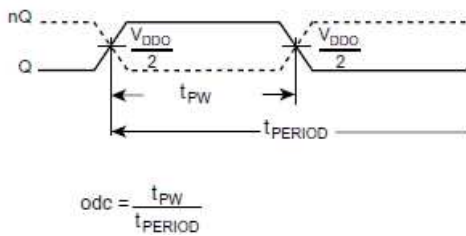
Measured at $V_{DDO}/2$.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDO}/2$.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

PARAMETER MEASUREMENT INFORMATION


3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT

3.3V/2.5V OUTPUT LOAD AC TEST CIRCUIT

PROPAGATION DELAY

OUTPUT SKEW

PART-TO-PART SKEW

OUTPUT RISE/FALL TIME

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

RELIABILITY INFORMATION

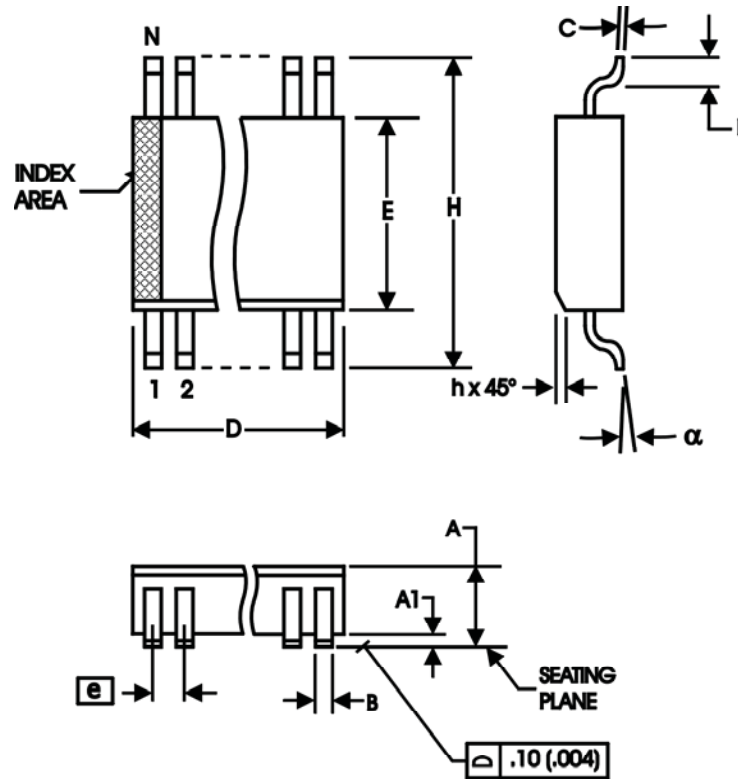
TABLE 5. θ_{JA} vs. AIR FLOW TABLE FOR 8 LEAD SOIC

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for 8302I-01 is: 322

PACKAGE OUTLINE - SUFFIX M FOR 8 LEAD SOIC

TABLE 6. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MINIMUM	MAXIMUM
N	8	
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BASIC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012

TABLE 7. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83054AGI-01LF	054AI01L	16 lead "Lead Free" TSSOP	Tray	-40°C to +85°C
83054AGI-01LFT	054AI01L	16 lead "Lead Free" TSSOP	Tape and Reel	-40°C to +85°C

REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
A	T7	8 10	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	7/29/10
A	T7	1 8	Features section - removed reference to leaded package. Ordering Information - removed quantity from tape and reel. Deleted LF note below table. Updated header and footer.	3/9/16

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